



Product Change Notification: CAAN-24KWHR576

Date:

25-Jun-2026

Product Category:

16-Bit Microcontrollers, 32-Bit Microcontrollers, 8-Bit Microcontrollers, Digital Signal Controllers

Notification Subject:

CCB 8364 Initial Notice: Qualification of of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected dsPIC33EP128xx, dsPIC33EP256xx, dsPIC33EP512xx, PIC18F96J94, PIC18F97J94, PIC24EP256GU810, PIC24EP512GU810, PIC24FJ128GA310, PIC32MX1xx, PIC32MX2xx, PIC32MX3xx, PIC32MX4xx, PIC32MX5xx, PIC32MX6xx and PIC32MX7xx device families available in 100L TQFP (14x14x1mm) package assembled at MMT site.

Affected CPNs:

[CAAN-24KWHR576_Affected_CPN_06252026.pdf](#)

[CAAN-24KWHR576_Affected_CPN_06252026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected dsPIC33EP128xx, dsPIC33EP256xx, dsPIC33EP512xx, PIC18F96J94, PIC18F97J94, PIC24EP256GU810, PIC24EP512GU810, PIC24FJ128GA310, PIC32MX1xx, PIC32MX2xx, PIC32MX3xx, PIC32MX4xx, PIC32MX5xx, PIC32MX6xx and PIC32MX7xx device families available in 100L TQFP (14x14x1mm) package assembled at MMT site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS-free)	QMI519 (PFAS-free)	No
Molding Compound Material	G700HA	G700HA	No
Lead-Frame Material	C7025	C7025	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: August 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	June 2026					>	August 2026				
Work Week	23	24	25	26	27		32	33	34	35	36
Initial PCN Issue Date					X						
Qual Report Availability										X	
Final PCN Issue Date										X	

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: June 25, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_CAAN-24KWHR576_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

PIC32MX564F064LT-I/PF
PIC32MX564F064LT-V/PF
PIC32MX564F064L-V/PF
PIC32MX564F128L-I/PF
PIC32MX564F128LT-I/PF
PIC32MX564F128LT-V/PF
PIC32MX564F128L-V/PF
PIC32MX570F512L-50I/PF
PIC32MX570F512L-I/PF
PIC32MX570F512LT-50I/PF
PIC32MX570F512LT-I/PF
PIC32MX570F512LT-V/PF
PIC32MX570F512L-V/PF
PIC32MX575F256L-80I/PF
PIC32MX575F256L-80V/PF
PIC32MX575F256LT-80I/PF
PIC32MX575F256LT-80V/PF
PIC32MX575F256LT-80V/PFC21
PIC32MX575F512L-80I/PF
PIC32MX575F512L-80V/PF
PIC32MX575F512LT-80I/PF
PIC32MX575F512LT-80V/PF
PIC32MX664F064L-I/PF
PIC32MX664F064LT-I/PF
PIC32MX664F064LT-V/PF
PIC32MX664F064L-V/PF
PIC32MX664F128L-I/PF
PIC32MX664F128LT-I/PF
PIC32MX664F128LT-V/PF
PIC32MX664F128L-V/PF
PIC32MX675F256L-80I/PF
PIC32MX675F256L-80V/PF

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PIC32MX675F256LT-80V/PF

PIC32MX675F512L-80I/PF

PIC32MX675F512L-80V/PF

PIC32MX675F512LT-80I/PF

PIC32MX675F512LT-80V/PF

PIC32MX695F512L-80I/PF

PIC32MX695F512L-80V/PF

PIC32MX695F512LT-80I/PF

PIC32MX695F512LT-80V/PF

PIC32MX764F128L-I/PF

PIC32MX764F128LT-I/PF

PIC32MX764F128LT-V/PF

PIC32MX764F128L-V/PF

PIC32MX775F256L-80I/PF

PIC32MX775F256L-80V/PF

PIC32MX775F256LT-80I/PF

PIC32MX775F256LT-80V/PF

PIC32MX775F512L-80I/PF

PIC32MX775F512L-80V/PF

PIC32MX775F512LT-80I/PF

PIC32MX775F512LT-80V/PF

PIC32MX795F512L-80I/PF

PIC32MX795F512L-80I/PFE21

PIC32MX795F512L-80V/PF

PIC32MX795F512LT-80I/PF

PIC32MX795F512LT-80V/PF

DSPIC33EP128GM310-I/PF

DSPIC33EP128GM710-E/PF

DSPIC33EP128GM710-I/PF

DSPIC33EP128GM710T-I/PF

DSPIC33EP256GM310-E/PF

DSPIC33EP256GM310-I/PF

DSPIC33EP256GM710-I/PF

DSPIC33EP256MU810-E/PF

DSPIC33EP256MU810-I/PF

DSPIC33EP256MU810T-E/PF

DSPIC33EP256MU810T-I/PF

DSPIC33EP512GM310-E/PF

DSPIC33EP512GM310-I/PF

DSPIC33EP512GM310T-I/PF

DSPIC33EP512GM710-E/PF

DSPIC33EP512GM710-I/PF

DSPIC33EP512MU810-E/PF

DSPIC33EP512MU810-I/PF

DSPIC33EP512MU810-I/PFC04

DSPIC33EP512MU810T-E/PF

DSPIC33EP512MU810T-I/PF

PIC18F96J94-I/PF

PIC18F96J94T-I/PF

PIC18F97J94-I/PF

PIC24EP256GU810-E/PF

PIC24EP256GU810-I/PF

PIC24EP256GU810T-E/PF

PIC24EP256GU810T-I/PF

PIC24EP512GU810-E/PF

PIC24EP512GU810-I/PF

PIC24EP512GU810T-E/PF

PIC24EP512GU810T-I/PF

PIC24FJ128GA310-I/PF

PIC32MX130F128L-50I/PF

PIC32MX130F128L-I/PF

PIC32MX130F128LT-50I/PF

PIC32MX130F128LT-I/PF

PIC32MX130F128LT-V/PF

PIC32MX130F128L-V/PF

PIC32MX150F256L-50I/PF

PIC32MX150F256L-I/PF

PIC32MX150F256LT-50I/PF

PIC32MX150F256LT-I/PF

PIC32MX150F256LT-V/PF

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PIC32MX150F256L-V/PF

PIC32MX170F512L-50I/PF

PIC32MX170F512L-I/PF

PIC32MX170F512LT-50I/PF

PIC32MX170F512LT-I/PF

PIC32MX170F512LT-V/PF

PIC32MX170F512L-V/PF

PIC32MX230F128L-50I/PF

PIC32MX230F128L-I/PF

PIC32MX230F128LT-50I/PF

PIC32MX230F128LT-I/PF

PIC32MX230F128LT-V/PF

PIC32MX230F128L-V/PF

PIC32MX250F256L-50I/PF

PIC32MX250F256L-I/PF

PIC32MX250F256LT-50I/PF

PIC32MX250F256LT-I/PF

PIC32MX250F256LT-V/PF

PIC32MX250F256L-V/PF

PIC32MX270F512L-50I/PF

PIC32MX270F512L-I/PF

PIC32MX270F512LT-50I/PF

PIC32MX270F512LT-I/PF

PIC32MX270F512LT-V/PF

PIC32MX270F512L-V/PF

PIC32MX330F064L-I/PF

PIC32MX330F064LT-I/PF

PIC32MX330F064LT-V/PF

PIC32MX330F064L-V/PF

PIC32MX350F128L-I/PF

PIC32MX350F128LT-I/PF

PIC32MX350F128LT-V/PF

PIC32MX350F128L-V/PF

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PIC32MX350F256LT-I/PF

PIC32MX350F256LT-V/PF

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PIC32MX350F256L-V/PF

PIC32MX370F512L-I/PF

PIC32MX370F512LT-I/PF

PIC32MX370F512LT-V/PF

PIC32MX370F512L-V/PF

PIC32MX430F064L-I/PF

PIC32MX430F064LT-I/PF

PIC32MX430F064LT-V/PF

PIC32MX430F064L-V/PF

PIC32MX450F128L-I/PF

PIC32MX450F128LT-I/PF

PIC32MX450F128LT-V/PF

PIC32MX450F128L-V/PF

PIC32MX450F256L-120/PF

PIC32MX450F256L-I/PF

PIC32MX450F256LT-120/PF

PIC32MX450F256LT-I/PF

PIC32MX450F256LT-V/PF

PIC32MX450F256L-V/PF

PIC32MX470F512L-120/PF

PIC32MX470F512L-I/PF

PIC32MX470F512LT-120/PF

PIC32MX470F512LT-I/PF

PIC32MX470F512LT-V/PF

PIC32MX470F512L-V/PF

PIC32MX530F128L-50I/PF

PIC32MX530F128L-I/PF

PIC32MX530F128LT-50I/PF

PIC32MX530F128LT-I/PF

PIC32MX530F128LT-V/PF

PIC32MX530F128L-V/PF

PIC32MX534F064L-I/PF

PIC32MX534F064LT-I/PF

PIC32MX534F064LT-V/PF

PIC32MX534F064L-V/PF

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PIC32MX550F256L-I/PF

PIC32MX550F256LT-50I/PF

PIC32MX550F256LT-I/PF

PIC32MX550F256LT-V/PF

PIC32MX550F256L-V/PF

PIC32MX564F064L-I/PF



QUALIFICATION PLAN SUMMARY

PCN#: CAAN-24KWHR576

**Date:
June 29, 2026**

Qualification of of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected dsPIC33EP128xx, dsPIC33EP256xx, dsPIC33EP512xx, PIC18F96J94, PIC18F97J94, PIC24EP256GU810, PIC24EP512GU810, PIC24FJ128GA310, PIC32MX1xx, PIC32MX2xx, PIC32MX3xx, PIC32MX4xx, PIC32MX5xx, PIC32MX6xx and PIC32MX7xx device families available in 100L TQFP (14x14x1mm) package assembled at MMT site.

Purpose: Qualification of of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected dsPIC33EP128xx, dsPIC33EP256xx, dsPIC33EP512xx, PIC18F96J94, PIC18F97J94, PIC24EP256GU810, PIC24EP512GU810, PIC24FJ128GA310, PIC32MX1xx, PIC32MX2xx, PIC32MX3xx, PIC32MX4xx, PIC32MX5xx, PIC32MX6xx and PIC32MX7xx device families available in 100L TQFP (14x14x1mm) package assembled at MMT site.

CCB No.: 8364

<u>Misc.</u>	Assembly site	MMT
	BD Number	BD-004440/01
	MP Code (MPC)	TDAA19E5XCC8
	Part Number (CPN)	PIC32MX575F512L-80V/PF
	MSL information	MSL-1
	Assembly Shipping Media (T/R, Tube/Tray)	Tray
	Base Quantity Multiple (BQM)	90
	Reliability Site	MTAI
<u>Lead-Frame</u>	Paddle size	280x280 mils
	Material	C7025
	DAP Surface Prep	Bare Cu
	Treatment	None
	Process	C7025
	Part Number	10110015
	Lead Plating	Matte Tin
	Strip Size	250x70mm
	Strip Density	30 units/strip
<u>Bond Wire</u>	Material	CuPdAu
<u>Die Attach</u>	Part Number	QMI519 (PFAS-free)
	Conductive	Yes
<u>MC</u>	Part Number	G700HA
<u>PKG</u>	Package Type	TQFP
	Pin/Ball Count	100
	PKG width/size	14x14x1.0mm

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Pkg. Type	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5		MMT/MTAI	TQFP	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5		MMT/MTAI	TQFP	30 bonds from a min. 5 devices.
Wire Sweep											
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5				
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5		MMT/MTAI	TQFP	
HTSL (High Temp Storage Life)	JESD22-A103. +175 C for 504 hours Electrical test pre and post stress at +25°C and 125°C hot temp.	45	5	3	150	0	10	MTAI	MTAI	TQFP	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. MSL-1/260C	231	15	3	738	0	15	MTAI	MTAI	TQFP	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A110. +130°C/85% RH for 96 hours Electrical test pre and post stress at +25°C and 125°C hot temp.	77	5	3	246	0	10	MTAI	MTAI	TQFP	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A118. +130°C/85% RH for 96 hrs Electrical test pre and post stress at +25°C	77	5	3	246	0	10	MTAI	MTAI	TQFP	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles. Electrical test pre and post stress at 125°C hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	MTAI	MTAI	TQFP	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.